

WHAT IS CLAIMED IS:

1. A circuit device comprising:

a conductive pattern on which a circuit element is mounted;

5 an insulating resin with which the circuit element and the conductive pattern are covered;

a shielding layer provided on the insulating resin, and

a connecting means for electrically connecting the conductive pattern to the shielding layer.

10 2. The circuit device as set forth in Claim 1, wherein the insulating resin has a through-hole so as to partially expose a surface of the conductive pattern, and the connecting means is formed at a bottom face of and at a side face of the through-hole.

15 3. The circuit device as set forth in Claim 1, wherein the conductive pattern electrically connected to the shielding layer is a conductive pattern serving as a ground potential.

4. The circuit device as set forth in Claim 1, wherein the shielding layer is made from a metal.

20 5. The circuit device as set forth in Claim 1, wherein the shielding layer and the connecting means are made of the same material.

6. The circuit device as set forth in Claim 1, wherein

the shielding layer and the connecting means are made of a plated film.

7. The circuit device as set forth in Claim 1, wherein an upper surface of the insulating resin is a rugged surface.

5 8. The circuit device as set forth in Claim 1, wherein backface of the conductive pattern is exposed.

9. A method for manufacturing a circuit device, the method comprising:

preparing a conductive foil;

10 forming separation grooves the depth of each of which is smaller than a thickness of the conductive foil and forming a plurality of conductive patterns;

fixing a circuit element to the conductive pattern;

performing a molding operation so that the circuit
15 element is covered with an insulating resin and so that the separation grooves are filled with the insulating resin;

forming a through-hole in the insulating resin so that the conductive pattern is exposed;

forming a shielding layer on a surface of the insulating
20 resin and, concurrently, forming a connecting means at a side face of and a bottom face of the through-hole;

removing a backface of the conductive foil until the insulating resin is exposed; and

dividing the insulating resin for each individual circuit device by dicing the insulating resin.

10. The method for manufacturing a circuit device as set forth in Claim 9, wherein the through-hole is formed by use
5 of a laser.

11. The method for manufacturing a circuit device as set forth in Claim 9, wherein the shielding layer and the connecting means are formed according to a plating method.

12. The method for manufacturing a circuit device as set
10 forth in Claim 9, wherein a part of the shielding layer that corresponds to a borderline between circuit devices is removed.